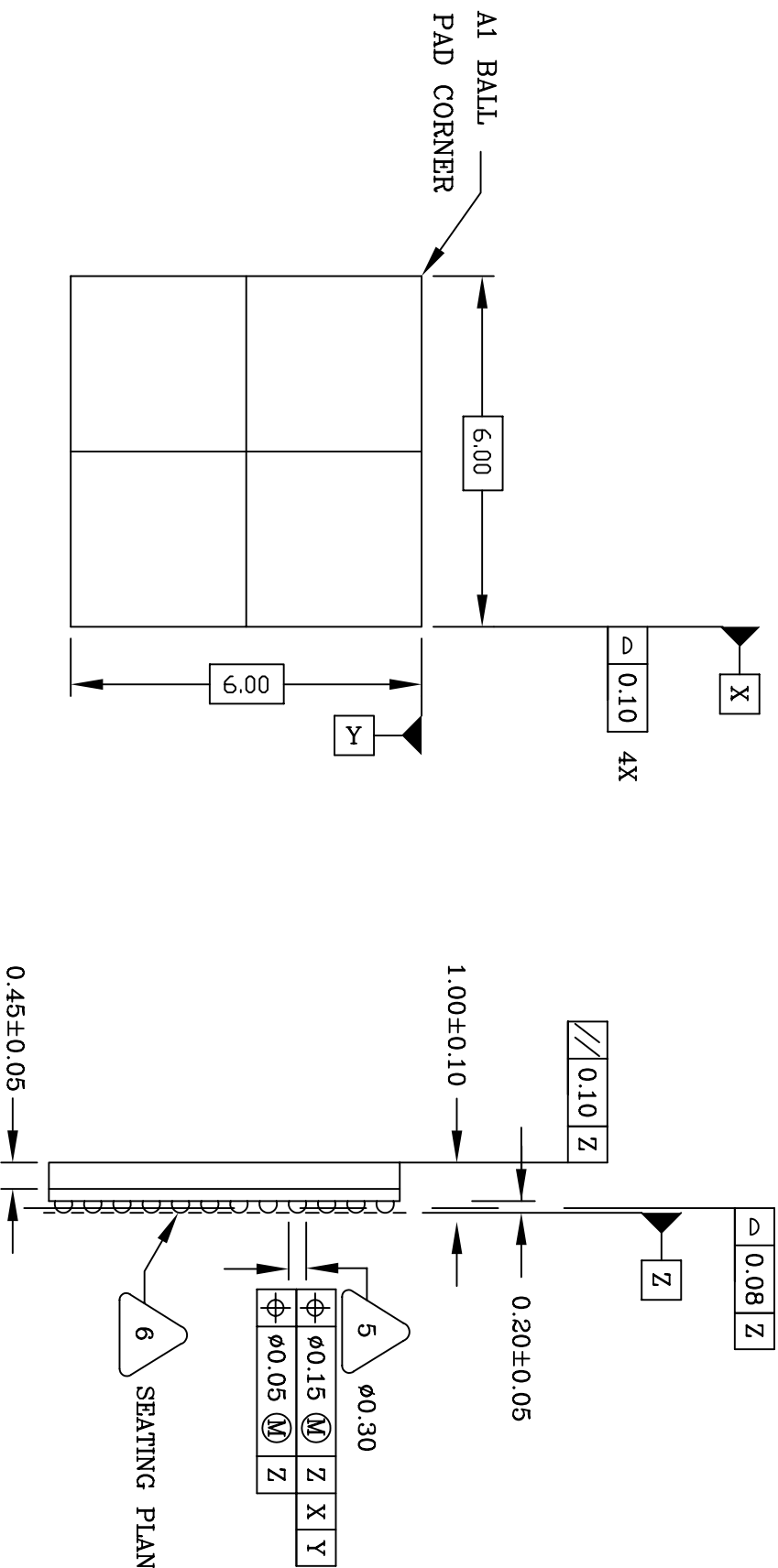


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	08/25/03	DP
01	ADD 'GREEN' BYG NOMENCLATURE	11/17/04	DP
02	Moldcap Thickness Updated	08/03/05	DP
03	Combine PDD & Land Pattern	05/20/13	RC



TOP VIEW

SIDE VIEW

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
DECIMAL
XX ±0.10
XXX ±0.05
XXXX ±0.05

APPROVALS: DATE: 8/25/03
DRAWN: JJC
CHECKED:

BY/BYG 100 PACKAGE OUTLINE
6.0 X 6.0 X 1.0 mm BDDY CVBGA
0.5 mm Ball Pitch

DRAWING No. PSC-4123

6024 Silver Creek Valley Road
San Jose, CA 95138
PHONE: (408) 284-8200
FAX: (408) 496-8591

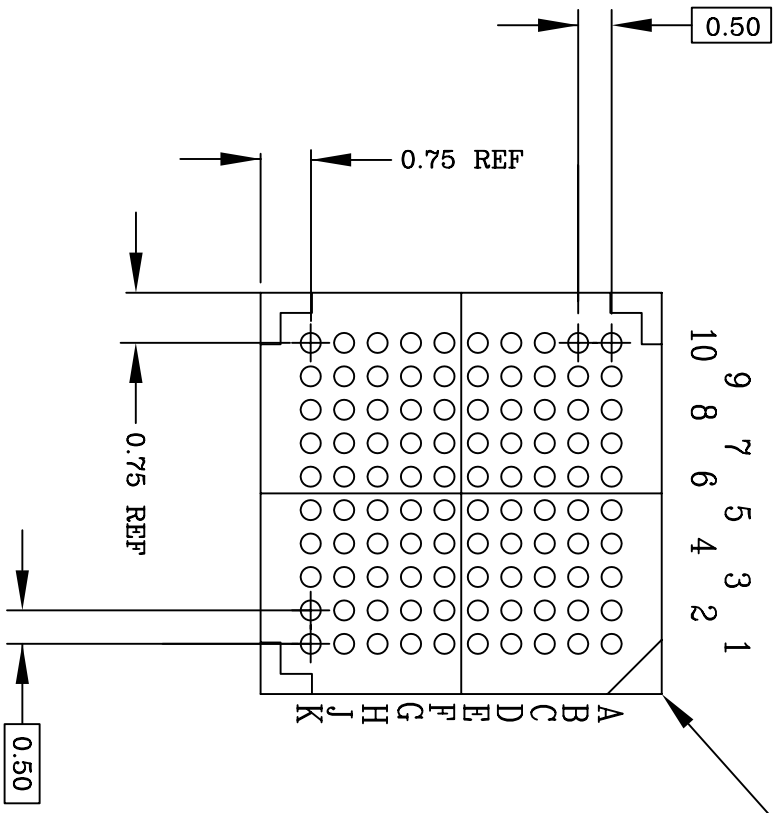
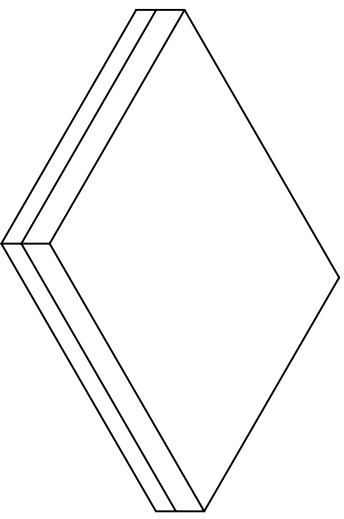
www.IDT.com

SIZE: C SCALE: N/A REV: 03

DD NOT SCALE DRAWING SHEET 1 OF 3

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	08/25/03	DP
01	ADD 'GREEN' BYG NDMENCLATURE	11/17/04	DP
02	MOLD CAP THICKNESS UPDATED	08/03/05	DP
03	Combine PDD & Land Pattern	05/20/13	RC

A1 BALL PAD CORNER

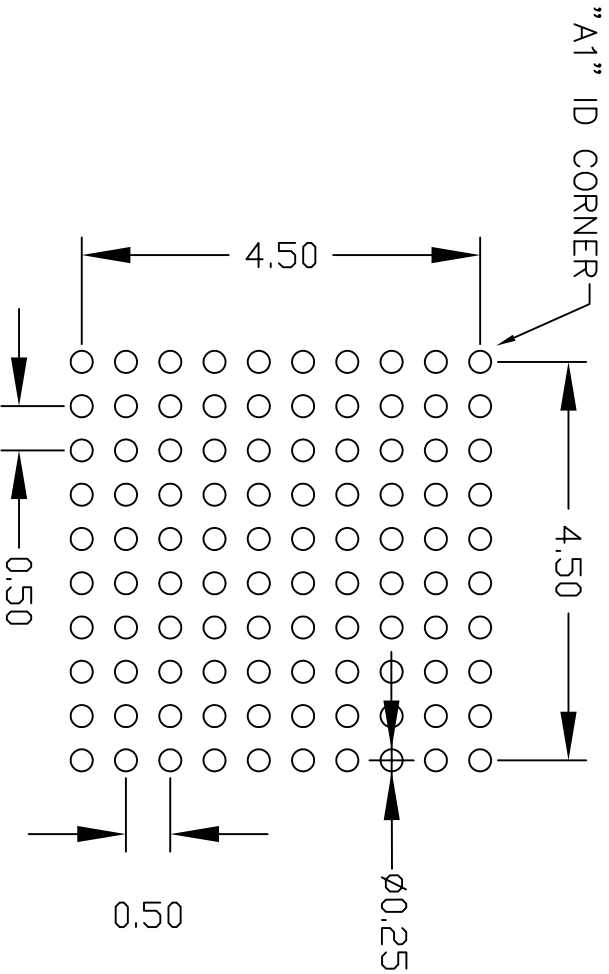


BOTTOM VIEW
(100 SOLDER BALLS)

- NOTES: UNLESS OTHERWISE SPECIFIED
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
 2. THE BASIC SOLDER BALL GRID PITCH IS 0.50.
 3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 10 X 10.
 4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 100.
 5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
 6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 7. *A1* ID CORNER MUST BE IDENTIFIED BY CHAMFER, INK MARK, METALLIZED MARKING, INDENTATION OR OTHER FEATURE ON PACKAGE BODY.
 8. IF "A1" ID CORNER IS ON PACKAGE BODY. IT MUST BE LOCATED WITHIN THE ZONE INDICATED.
 9. ALL DIMENSIONS ARE IN MILLIMETERS.

<small>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS DECIMAL ANGULAR XX ±0.10 XXX ±0.05 XXXX ±0.03</small>				6024 Silver Creek Valley Road SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591	
APPROVALS	DATE	BY/BYG	DRAWING No.	SIZE	SCALE
DRWN JGS	08/25/03	100 PACKAGE DUTLINE	PSC-4123	C	N/A
CHECKED		5.0 X 5.0 X1.0mm BODY CVBGA			REV
		0.5 mm Ball Pitch			03
WWW.IDT.COM			DD NOT SCALE DRAWING		
			SHEET 2 OF 3		


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	08/25/03	DP
01	ADD 'GREEN' BYG NOMENCLATURE	11/17/04	DP
02	MULDICAP THICKNESS UPDATED	08/03/05	DP
03	Combine PDD & Land Pattern	05/20/13	RC



RECOMMENDED LAND PATTERN DIMENSION (mm)

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		 IDT 6024 Silver Creek Valley Road San Jose CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572
DECIMAL	ANGULAR	
XX.X	.1°	WWW.IDT.COM TITLE BY/BYG100 LAND PATTERN 6.0 x 6.0 mm BODY CYBGA 0.5 mm PITCH
XXX.X	.030	
APPROVALS	DATE	SIZE DRAWING No. REV C PSC-4123 03
DRAWN: AS	8/25/03	
CHECKED		DO NOT SCALE DRAWING
		SHEET 3 OF 3